

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



	TEC	HNICAL DATA SH	HEET	2 / 5
RIGHT A	NGLE JACK RE	OR PCB	R113.664.120	
	SOLDER		Series : MCX	
PACKAGING			<b>SPECIFICATION</b>	
Standard 500	Unit	Other Contact us		
500	-	Contact us		
ELECTRICAL CHARACTERISTICS			ENVIRONMENTAL	
Impedance Frequency VSWR Insertion loss RF leakage Voltage rating	0-0 1.25 + 0.00 0.00 - ( NA	<ul> <li>Ω</li> <li>GHz</li> <li>x F(GHz) Maxi</li> <li>√F(GHz) dB Maxi</li> <li>- F(GHz)) dB mini</li> <li>Veff Maxi</li> </ul>	Operating temper Hermetic seal Panel leakage	rature -55/+155 ° C NA Atm.cm3/s NA
Dielectric withstanding voltage 10		0 Veff mini 0 MΩ mini	OTHERS CHARACTERISTICS	
			Assembly instruc	ction
			Others :	
MECHAN	ICAL CHARACTI	ERISTICS	-	
Center contact retent	ion			
Axial force – Mating end		0 N mini		
Axial force – Oppo		N mini N.cm mini		
Torque	INF			
Recommended torqu				
Mating Panel nut		N.cm N.cm		
Mating life Weight	50 1.64	<ul><li><b>0</b> Cycles mini</li><li><b>0</b> g</li></ul>		
<b>Issue :</b> 0420 B	1 4			
In the effort to improve necessary.	e our products, we reserv	e the right to make ch	anges judged to be	

#### TECHNICAL DATA SHEET

### **RIGHT ANGLE JACK RECEPTACLE FOR PCB**

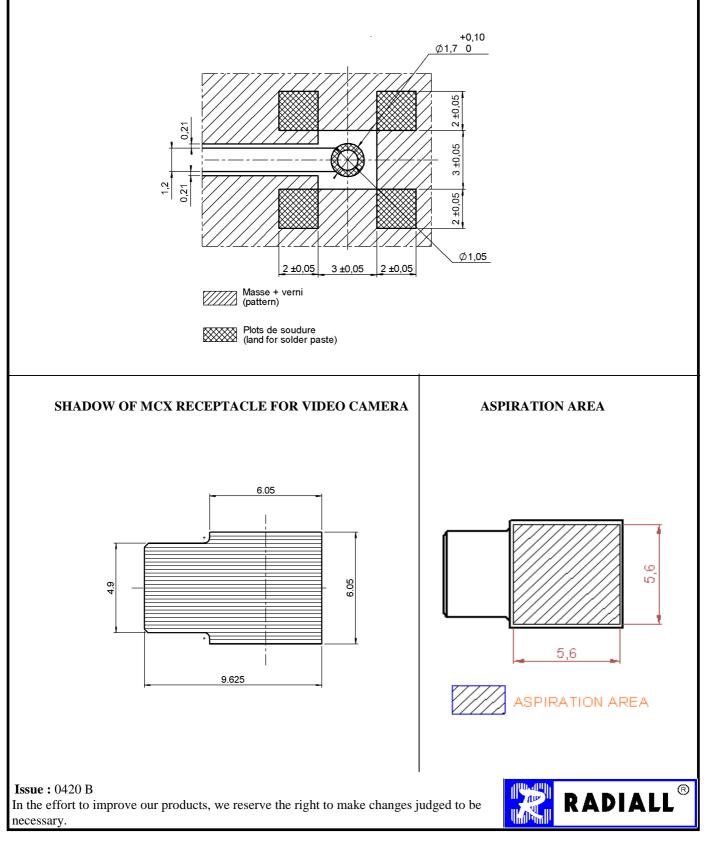
#### **SOLDER LEGS**

Series : MCX

R113.664.120

#### **MCX SERIES - INFORMATION**

Coplanar line : pattern and signal are on the same side . Thickness of PCB :.079(2mm) The material of PCB is the epoxy resin of glass fabrics bacs . (Er = 4.8) . The solder resist should be printed exept for the land pattern on the PCB .



#### TECHNICAL DATA SHEET

# **RIGHT ANGLE JACK RECEPTACLE FOR PCB**

### SOLDER LEGS

Series : MCX

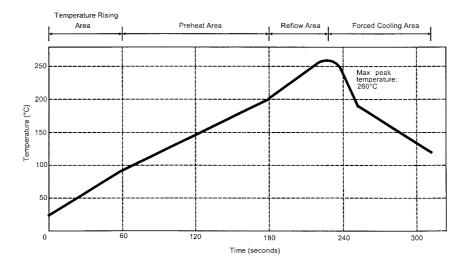
R113.664.120

### SOLDER PROCEDURE

1. Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.

We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.

- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. Video camera is prefered to check the positioning of the compnent. Adhesive agents are forbidden on the receptacle.
- 3. Soldering by infra-red reflow.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.



## **TEMPERATURE PROFILE**

Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

